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IDENTIFIER:

US 5930677 A

TITLE:

Method for reducing microloading in an etchback of spin-on-glass or polymer

TITLE - TI (1):

Method for reducing microloading in an etchback of spin-on-glass or polymer

Detailed Description Text - DETX (12):

The process of the invention results in excellent planarization and uniformity of an interlevel dielectric layer with significantly reduced microloading effect at the spin-on-glass etchback step and elimination of keyhole defects. The addition of O.sub.2 to the etchback plasma is much more than the extra release of oxygen when the first oxide layer is exposed; therefore, the microloading effect of the extra release of oxygen is greatly reduced by the process of the invention.